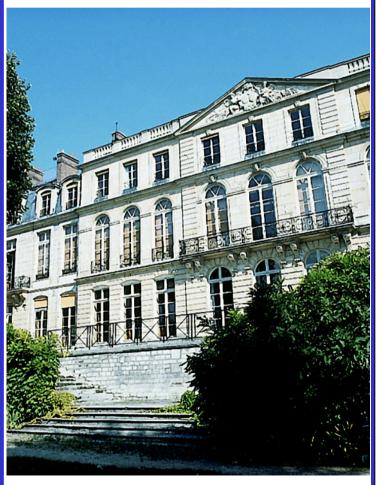
ECCMR 2007

Fifth European Conference on Constitutive Models for Rubber

Ecole Nationale Supérieure des Mines de Paris

> 60-62, Boulevard Saint Michel, 75272 PARIS cedex 06, FRANCE

Paris, 4-7 September 2007



http://eccmr.egim-mrs.fr

History

This conference is the fifth in the series on constitutive modelling of rubber.

The previous conferences, in Vienna (1999), Hannover (2001), London (2003) and Stockholm (2005), were highly successful and attracted a large number of academic and industrial delegates from a wide range of disciplines.

Delegates are encouraged to register both from outside and within Europe.

Conference objectives

- To bring together specialists both in constitutive modelling and polymer science, software development engineers and practitioners of finite element analysis of elastomeric components.
- To broaden the scope of modelling beyond stress-strain behaviour, for example in order to include heat build up, friction, electrical properties and fatigue.
- To investigate microscopic mechanisms involved in elastomers in order to develop physically-motivated models.
- To discuss advances in modelling the properties of elastomers in order to improve the performance of available simulation tools dedicated to rubber parts.
- To collate these advances in hardbound Proceedings.

Conference themes

- Experimental characterisation of rubber properties
- Development and analysis of continuum mechanics models
- Numerical implementation and application of models
- Micro-structural observations and theories of rubber properties
- Fracture and fatigue
- Multi-physics aspects
- Structural applications and design issues of rubber components
- Biomechanical applications

Call for papers

The organisers invite prospective speakers to submit an abstract regarding any of the conference themes.

Instructions for online submission of abstract will be given on the conference homepage in September 2006: http://eccmr.egim-mrs.fr.

For more information, contact us at: eccmr@egim-mrs.fr.

Scientific committee

- Paul Buckley, University of Oxford, UK
- James Busfield, Queen Mary University of London, UK
- Luis Dorfmann, Tufts University, USA
- André Dragon, CNRS, France
- Alan Gent, University of Akron, USA
- Sanjay Govindjee, UC Berkeley, USA / ETH Zürich, Switzerland
- Gerhard Holzapfel, Graz University of Technology, Austria
- Michaël Kaliske, University of Leipzig, Germany
- Christian Miehe, Universitaet Stuttgart, Germany
- Alan Muhr, TARRC, UK
- Ray Ogden, University of Glasgow, UK
- Stefanie Reese, Technische Universität Braunschweig, Germany
- François Sidoroff, Ecole Centrale de Lyon, France

Organisers

The conference is organised by four french engineering high schools: Ecole Nationale Supérieure des Mines de Paris (ENSMP), Ecole Généraliste des Ingénieurs de Marseille (EGIM), Ecole Centrale de Nantes (ECN) and Ecole Polytechnique de l'Université de Tours (EPU Tours).

Organizing committee

- Gaëlle Berton, EPU Tours-LMR
- Adnane Boukamel, EGIM-LMA
- Sabine Cantournet, Centre des Matériaux, ENSMP
- Florian Lacroix, EPU Tours-LMR
- Lucien Laiarinandrasana,
 Centre des Matériaux, ENSMP
- Stéphane Lejeunes, EGIM-LMA
- Stéphane Méo, EPU Tours-LMR
- Erwan Verron, ECN-GeM

Time schedule

- Abstract deadline: 01/15/2007
- Full paper deadline: 04/15/2007
- Final acceptance: 06/15/2007

Conference fee

The conference fee will be approximately 400 €. This includes conference Proceedings, lunch for the four days, refreshments and the conference dinner.

All accepted papers will be published in a bound volume to be distributed to registered participants at the time of the conference.

Details of payment methods and other relevant information will be posted on the conference website in February 2007.

Venue

The conference venue is the Ecole Nationale Supérieure des Mines de Paris. The school is based in the heart of Paris (6th arrondissement), near the Jardins du Luxembourg.

More information can be found on http://eccmr.egim-mrs.fr.

Accommodation

A list of hotels will be available on the conference website.













